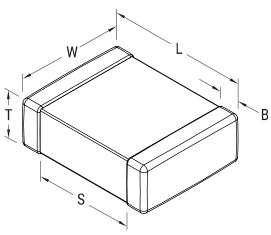




SMD Comm X8G HT150C Flex, Ceramic, 2,400 pF, 5%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.
4000

Dimensions		
Chip Size	1206	
L	3.3mm +/-0.4mm	
W	1.6mm +/-0.35mm	
Т	0.9mm +/-0.20mm	
S	1.5mm MIN	
В	0.6mm +/-0.25mm	

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

General Information				
Series	SMD Comm X8G HT150C Flex			
Style	SMD Chip			
Description	SMD, MLCC, High Temperature, Ultra-Stable			
Features	High Temperature, Ultra-Stable			
RoHS	Yes			
Termination	Flexible Termination			
Marking	No			
AEC-Q200	No			
Typical Component Weight	20 mg			
Shelf Life	78 Weeks			
MSL	1			

Specifications				
Capacitance	2,400 pF			
Measurement Condition	1 kHz 1.0Vrms			
Tolerance	5%			
Voltage DC	250 VDC			
Dielectric Withstanding Voltage	625 VDC			
Temperature Range	-55/+150°C			
Temp. Coefficient	X8G			
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms			
Dissipation Factor	0.1% 1 kHz 1.0Vrms			
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours			
Insulation Resistance	100 GOhms			

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 05/03/2025 © 2006 - 2025 YAGEO